

Quarterly Reliability Monitoring Results

Quarters: Q1/2022 to Q4/2023

Based on structural similarity

Supplier Nexperia B.V. Name of Laboratory Assembly reliability labs Based on AEC-Q101 Test		User Part Number PTVS3V3P1UP-Q Part Description										
								Nexperia DHAM Protection				
								SMD package				
		Test Conditions	Duration	# Lots	# Quantity	# Rejects						
			TEST									
			Pre- and Post-Stress									
# E1	Electrical Test	Tamb = 25 °C	N/A	see below	all parts	see below						
		JESD22-A113										
		Bake Tamb = 125 °C	24 hours									
	PC	Soak Tamb = 85 °C, RH = 85%	168 hours									
# A1	Preconditioning	Reflow soldering	3 cycles	524	22940	0						
		MIL-STD-750-1										
	HTRB	M1038 Method A										
	High Temperature Reverse Bias	Tj = Tjmax, Vr = 100% of max. datasheet				_						
# B1	DIdS	reverse voltage	1000 hours	205	9400	0						
	TC	JECD22 A104										
# 44	TC Temperature Cycling	JESD22-A104 -65 °C to Timax, not to exceed 150°C	1000	156	7000	0						
# A4	remperature cycling	os e to rimax, not to exceed 150 e	1000 cycles	156	7080	0						
	UHAST	JESD22-A118										
# A3 or	Unbiased HAST	Tamb = 130 °C, RH = 85 %		156	7080	0						
		JESD22-A102	– 96 hours									
	AC	Tamb = 121 °C, RH = 100 %										
# A3 alt	Autoclave	Pressure = 205 kPa (29.7 psia)										
		<u> </u>										
	НЗТ В	JESD22-A101										
	High Humidity High	Tamb = 85 °C, RH = 85%, VR = 80 % of										
# A2 alt	Temperature Reverse Bias	rated reverse voltage ^[1]	1000 hours	156	7080	0						
		MIL-STD-750 Method 1037										
	IOL	ton = toff, devices powered to insure ΔTj =										
# A5	Intermittent Operating Life	100 °C for 15000 cycles	1000 hours	n.a.	n.a.	n.a.						
	RSH	JESD22-A111										
# C8	Resistance to Solder Heat	260 °C ± 5 °C	10 s	56	1700	0						
	SD											
# C10	Solderability	J-STD-002		56	1700	0						

^[1] The maximum applied voltage is limited by test chamber set up and does not exceed 115V.

Calculation of FIT and MTTF

Test considered for FIT calculation: High Temperature Reverse Bias (HTRB, Test #B1) Confidence level 60%, derated to 55 °C, activation energy 0.7 eV, test time 168 to 1000 hours

Wafer Fab	Technology	Quantity	Rejects	Failure Rate (FIT)	MTTF (hrs)
Nexperia					
DHAM	Protection	9400	0	0,45	2,21E+09

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